

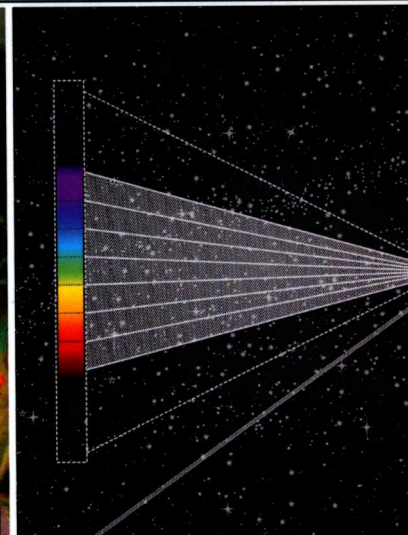
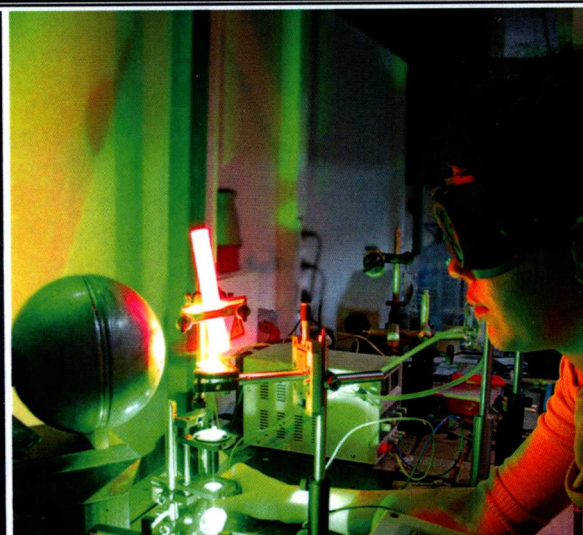
Volume II

Emissivity—Lenses



Encyclopedia of OPTICAL AND PHOTONIC ENGINEERING SECOND EDITION

Edited by
Craig Hoffman • Ronald Driggers

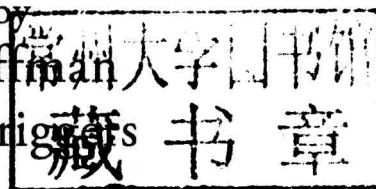


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